

SOT349-2

plastic quad flat package; 120 leads (lead length 1.6 mm);
body 28 x 28 x 3.4 mm; high stand-off height

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	QFP120
Package type industry code	QFP120
Package style descriptive code	QFP (quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	134E11
JEDEC package outline code	MS-022
Mounting method type	S (surface mount)
Issue date	25-2-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	27.9	-	28	28.1	mm
E	package width	27.9	-	28	28.1	mm
A	seated height	[tbd]	-	4.07	4.07	mm
A ₂	package height	3.15	-	3.4	3.7	mm
n ₂	actual quantity of termination	-	-	120	-	

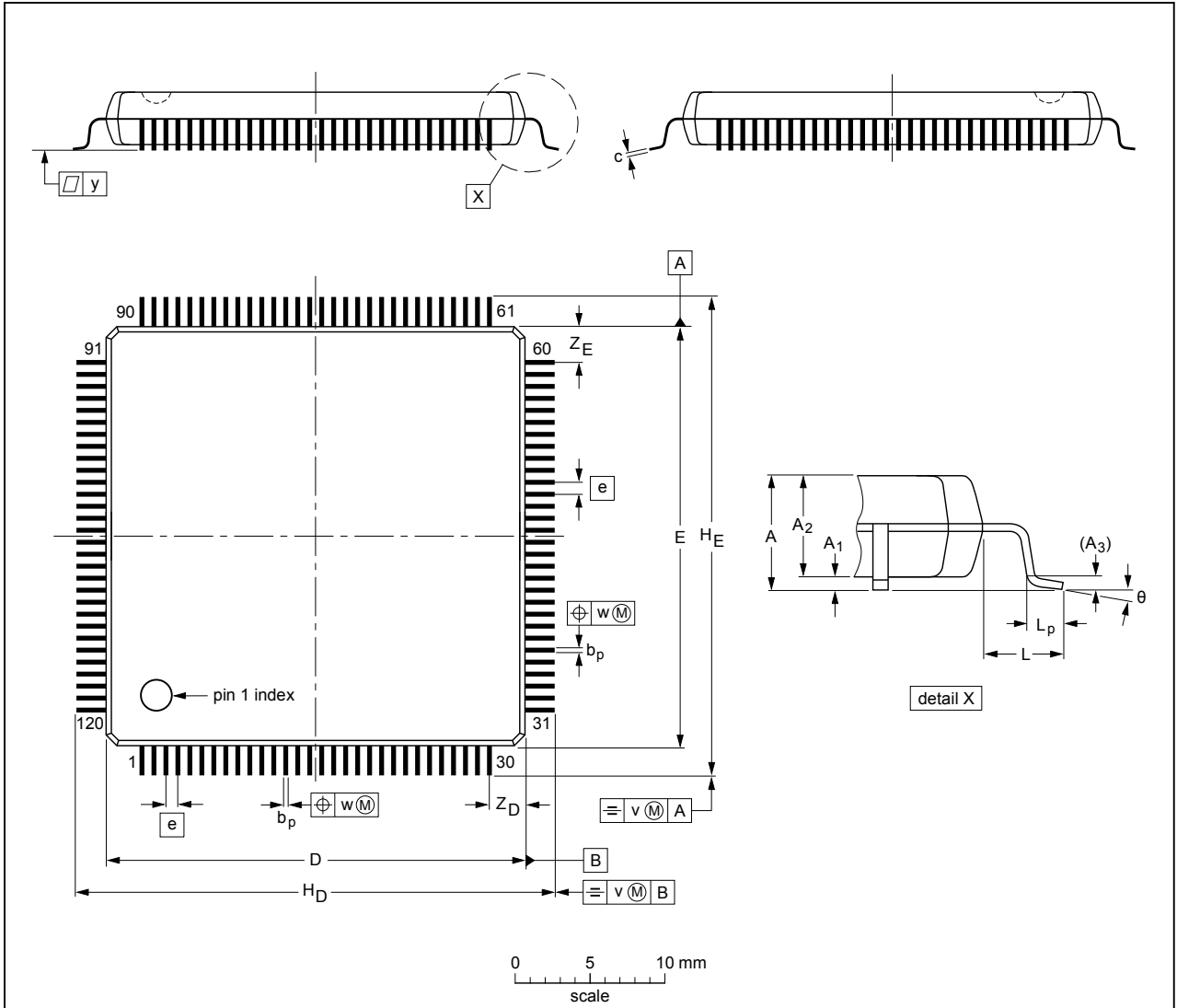


plastic quad flat package; 120 leads (lead length 1.6 mm); body 28 x 28 x 3.4 mm; high stand-off height

2. Package outline

QFP120: plastic quad flat package; 120 leads (lead length 1.6 mm); body 28 x 28 x 3.4 mm; high stand-off height

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _D	H _E	L	L _p	v	w	y	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
mm	4.07	0.50 0.25	3.70 3.15	0.25	0.45 0.30	0.23 0.13	28.1 27.9	28.1 27.9	0.8	31.45 30.95	31.45 30.95	1.6	1.03 0.73	0.3	0.2	0.1	2.6 2.2	2.6 2.2	7° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT349-2	134E11	MS-022			00-01-19 03-02-25

Fig. 1. Package outline QFP120 (SOT349-2)

plastic quad flat package; 120 leads (lead length 1.6 mm); body 28 x 28 x 3.4 mm; high stand-off height

3. Soldering

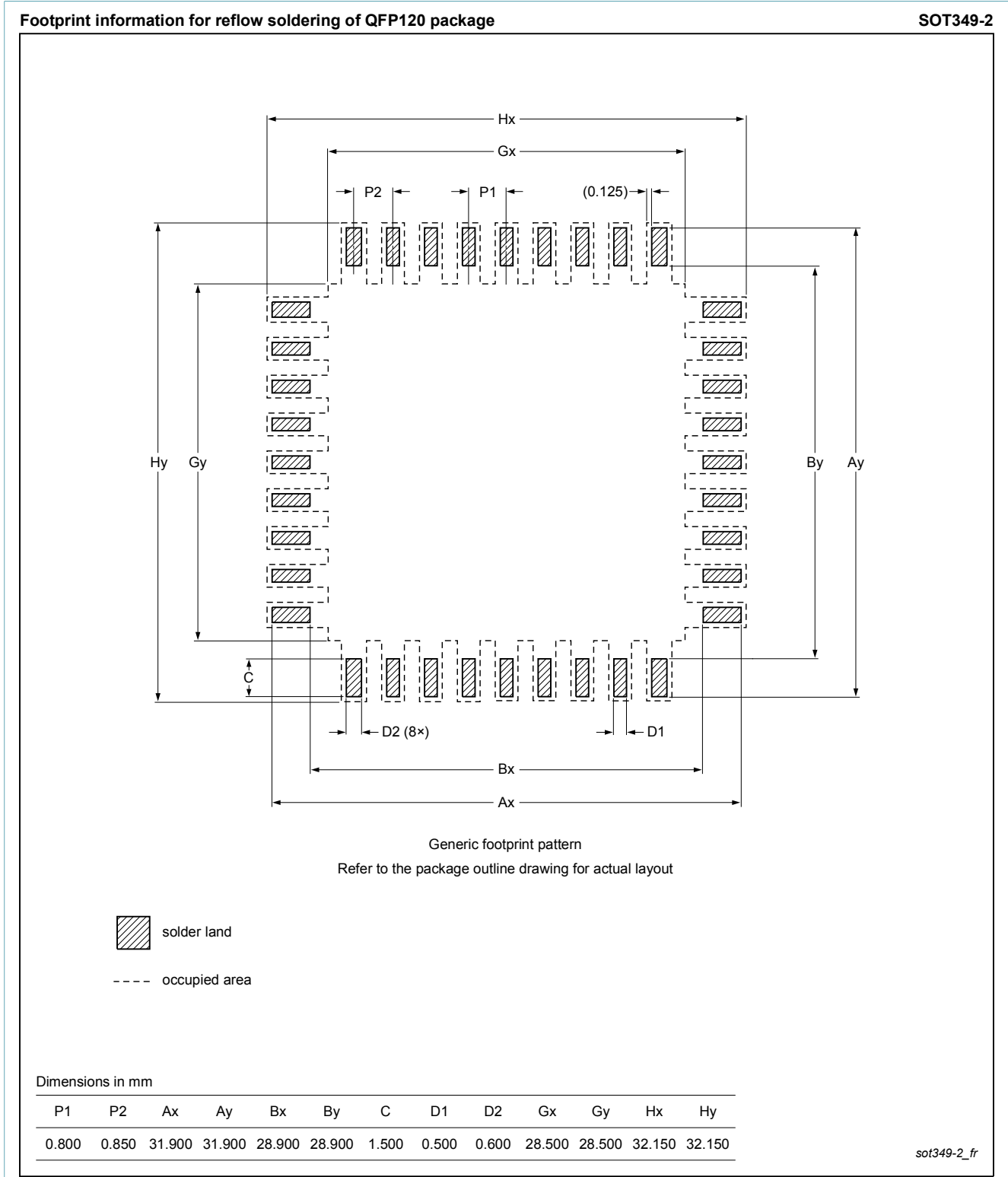


Fig. 2. Reflow soldering footprint for QFP120 (SOT349-2)

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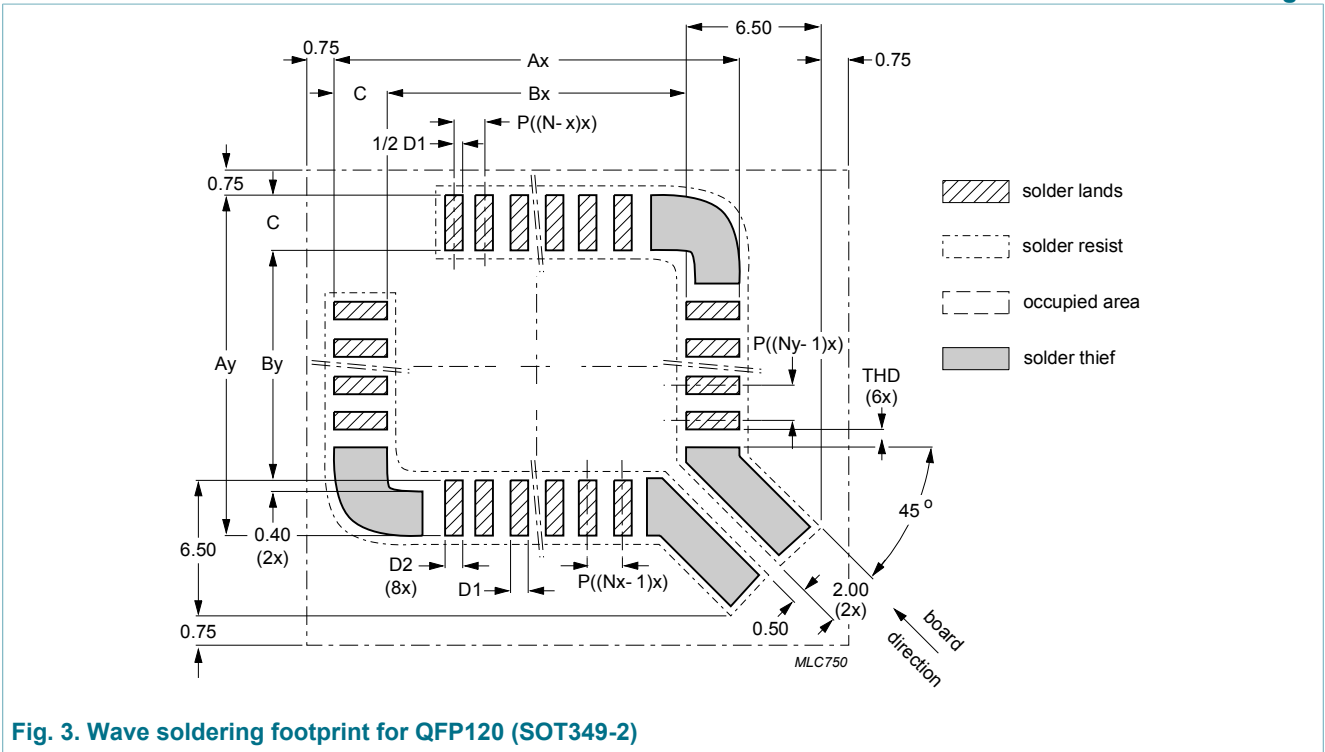


Fig. 3. Wave soldering footprint for QFP120 (SOT349-2)

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4. Legal information

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